

## FQP30N06 N-Channel QFET<sup>®</sup> MOSFET 60 V, 30 A, 40 mΩ

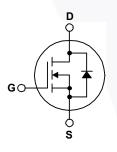
## Description

This N-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, audio amplifier, DC motor control, and variable switching power applications.

## Features

- 30 A, 60 V,  ${\rm R}_{\rm DS(on)}$  = 40 m $\Omega$  (Max.) @ V\_{\rm GS} = 10 V,  ${\rm I}_{\rm D}$  = 15 A
- Low Gate Charge (Typ. 19 nC)
- Low Crss (Typ. 40 pF)
- 100% Avalanche Tested
- 175°C Maximum Junction Temperature Rating





### Absolute Maximum Ratings T<sub>c</sub> = 25°C unless otherwise noted.

Symbol	Parameter		FQP30N06	Unit
V <sub>DSS</sub>	Drain-Source Voltage		60	V
I <sub>D</sub>	Drain Current - Continuous ( $T_C = 25^{\circ}C$ )		30	A
	- Continuous (T <sub>C</sub> = 100°C)		21.3	A
I <sub>DM</sub>	Drain Current - Pulsed	(Note 1)	120	Α
V <sub>GSS</sub>	Gate-Source Voltage		± 25	V
E <sub>AS</sub>	Single Pulsed Avalanche Energy	(Note 2)	280	mJ
I <sub>AR</sub>	Avalanche Current	(Note 1)	30	A
E <sub>AR</sub>	Repetitive Avalanche Energy	(Note 1)	7.9	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	7.0	V/ns
PD	Power Dissipation ( $T_C = 25^{\circ}C$ )		79	W
- Derate above 25°C			0.53	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +175	°C
TL	Maximum Lead Temperature for Soldering,		300	°C
	1/8" from Case for 5 seconds		300	C

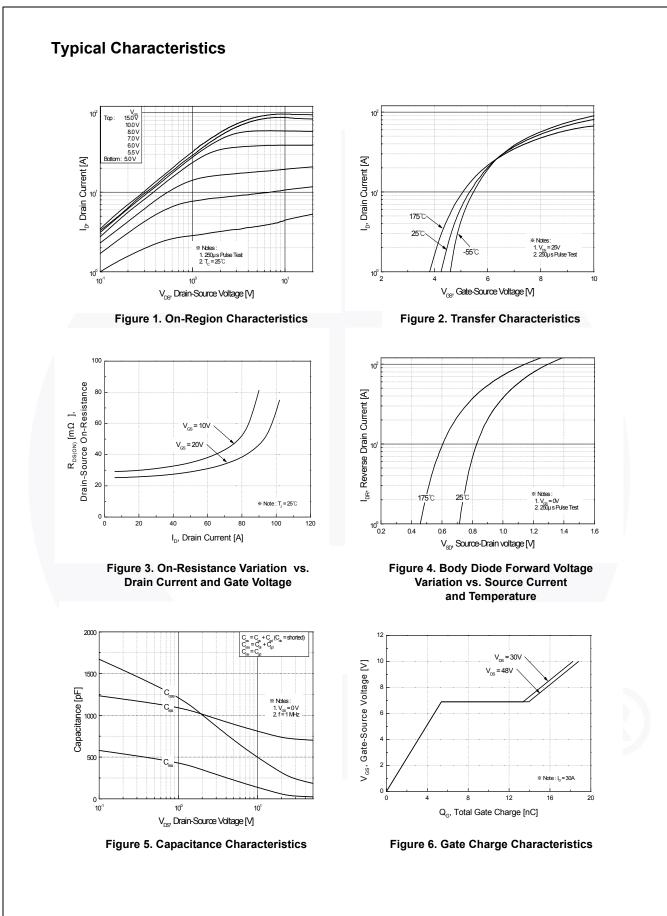
## **Thermal Characteristics**

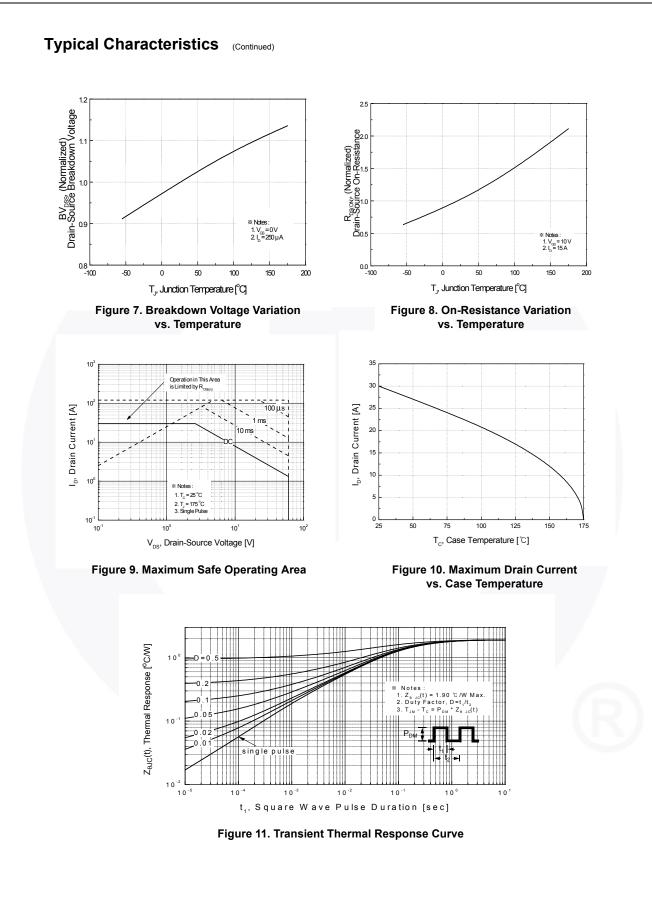
Symbol	Parameter	FQP30N06	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	1.90	°C/W
$R_{ extsf{ heta}JA}$	Thermal Resistance, Junction-to-Ambient, Max.	62.5	°C/W

November 2013

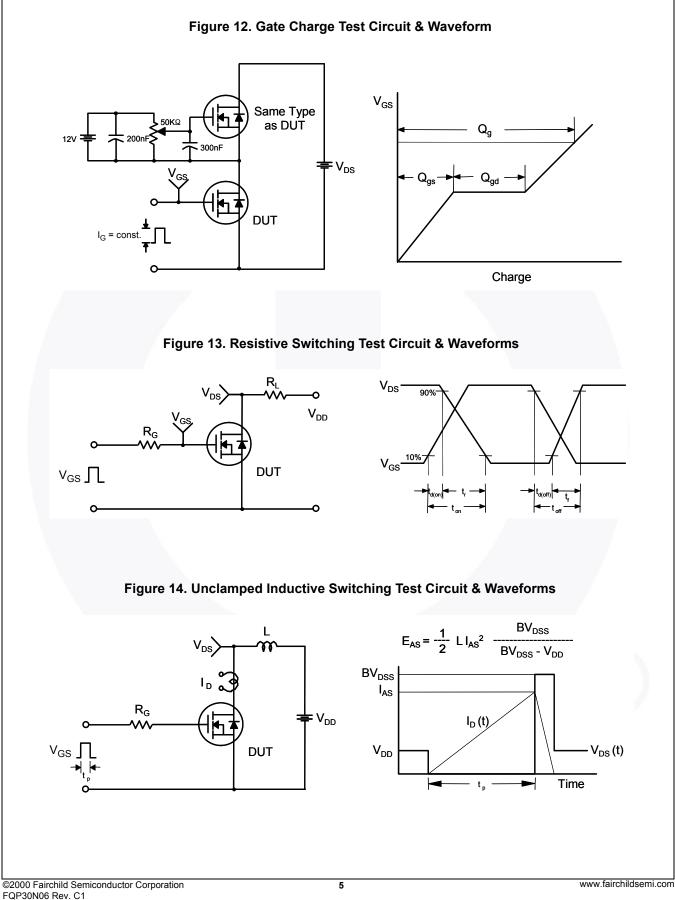
Part NumberTop MailFQP30N06FQP30N		Package TO-220	· · ·		Tape Width N/A			Quantity 50 units	
al Chara	acteristics T <sub>c</sub> :	- 25°C unless other	wise noted.						
	Parameter		Test Conditions		Min	Тур	Max	Unit	
ractoristic	re								
			$V_{CS} = 0 V. I_{D} = 250 I_{CS}$	ιA	60			V	
	<b>.</b>	oefficient	$V_{GS} = 0.0$ , $P_D = 250 \mu\text{A}$ $I_D = 250 \mu\text{A}$ , Referenced to 25°C			0.06		V/°C	
	ero Gate Voltage Drain Current		$V_{DS} = 60 V, V_{GS} = 0 V$				1	μA	
Zero Gate V							10	μΑ	
Gate-Body	Leakage Current, Forwa	ard					100	nA	
Gate-Body	Leakage Current, Rever	rse	$V_{GS}$ = -25 V, $V_{DS}$ = 0	V			-100	nA	
racteristic	s								
			V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA		2.0		4.0	V	
			$V_{GS} = 10 V, I_D = 15 A$			0.031	0.04	Ω	
Forward Tra	ansconductance		V <sub>DS</sub> = 25 V, I <sub>D</sub> = 15 A			16		S	
						705	0.45		
			V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V, f = 1.0 MHz					pF	
								pF	
Reverse IIa						40	52	pF	
ng Charao	teristics								
Turn-On De	lay Time		$V_{DD} = 30$ V, $I_D = 15$ A, R <sub>G</sub> = 25 Ω			10	30	ns	
Turn-On Ris	se Time					85	180	ns	
Turn-Off De	lay Time					35	80	ns	
Turn-Off Fa	ll Time			(Note 4)		40	90	ns	
Total Gate 0	Charge		V <sub>DS</sub> = 48 V, I <sub>D</sub> = 30 A	۹,		19	25	nC	
Gate-Sourc	e Charge					5.4		nC	
Gate-Drain			(Note 4)		8.5		nC		
	de Characteristic	and Mavi	mum Ratinge						
	Continuous Drain-Source		-				30	A	
Maximum Pulsed Drain-Source Diode Forward Current						120	A		
	ce Diode Forward Voltage		$V_{GS} = 0 \text{ V}, \text{ I}_{S} = 30 \text{ A}$				1.5	V	
Drain-Source									
	covery Time	,-	$V_{GS} = 0 V, I_{S} = 30 A,$			45		ns	
	racteristic Drain-Source Breakdown Zero Gate V Gate-Body I Gate-Body I Gate-Body I Gate-Body I racteristic Gate Threst Static Drain- On-Resistar Forward Tra C Charact Input Capac Output Capac Output Capac Output Capac Output Capac Output Capac Output Capac Turn-On De Turn-On De Turn-On Ris Turn-Off De Turn-Off Fal Total Gate C Gate-Source Gate-Drain	Parameter   racteristics   Drain-Source Breakdown Voltage   Breakdown Voltage Temperature Cd   Zero Gate Voltage Drain Current   Gate-Body Leakage Current, Forwa   Gate-Body Leakage Current, Rever   racteristics   Gate Threshold Voltage   Static Drain-Source   On-Resistance   Forward Transconductance   c Characteristics   Input Capacitance   Output Capacitance   Reverse Transfer Capacitance   nurn-On Delay Time   Turn-On Rise Time   Turn-Off Delay Time   Turn-Off Fall Time   Total Gate Charge   Gate-Source Charge   Gate-Drain Charge	Parameter   racteristics   Drain-Source Breakdown Voltage   Breakdown Voltage Temperature Coefficient   Zero Gate Voltage Drain Current   Gate-Body Leakage Current, Forward   Gate-Body Leakage Current, Reverse   racteristics   Gate Threshold Voltage   Static Drain-Source   On-Resistance   Forward Transconductance   Characteristics   Input Capacitance   Output Capacitance   Reverse Transfer Capacitance   Turn-On Delay Time   Turn-On Rise Time   Turn-Off Delay Time   Turn-Off Fall Time   Total Gate Charge   Gate-Source Charge   Gate-Source Charge   Gate-Drain Charge	ParameterTest ConditTest ConditracteristicsDrain-Source Breakdown Voltage $V_{GS} = 0 \ V, \ I_D = 250 \ \mu$ Breakdown Voltage Temperature Coefficient $I_D = 250 \ \mu$ A, ReferentZero Gate Voltage Drain Current $V_{DS} = 60 \ V, \ V_{GS} = 0$ Zero Gate Voltage Drain Current $V_{DS} = 60 \ V, \ V_{GS} = 0$ Gate-Body Leakage Current, Forward $V_{GS} = 25 \ V, \ V_{DS} = 0$ Gate-Body Leakage Current, Reverse $V_{GS} = -25 \ V, \ V_{DS} = 0$ Gate Threshold Voltage $V_{DS} = -25 \ V, \ V_{DS} = 0$ Static Drain-Source $V_{GS} = 10 \ V, \ I_D = 15 \ A$ Forward Transconductance $V_{DS} = 25 \ V, \ V_{GS} = 0$ Input Capacitance $V_{DS} = 25 \ V, \ V_{CS} = 0$ Output Capacitance $V_{DS} = 25 \ V, \ V_{CS} = 0$ furn-On Delay Time $V_{DD} = 30 \ V, \ I_D = 15 \ A$ Turn-On Rise Time $V_{DS} = 48 \ V, \ I_D = 15 \ A$ Turn-Off Fall Time $V_{DS} = 48 \ V, \ I_D = 30 \ A$ Turn-Off Fall Time $V_{DS} = 48 \ V, \ I_D = 30 \ A$ Turn-Off Fall Time $V_{DS} = 48 \ V, \ I_D = 30 \ A$ Turn-Off Fall Time $V_{DS} = 10 \ V$	ParameterTest ConditionsracteristicsDrain-Source Breakdown Voltage $V_{GS} = 0 V, I_D = 250 \mu A$ Breakdown Voltage Temperature Coefficient $I_D = 250 \mu A$ , Referenced to $25^{\circ}C$ Zero Gate Voltage Drain Current $V_{DS} = 60 V, V_{GS} = 0 V$ Zero Gate Voltage Drain Current $V_{DS} = 60 V, V_{GS} = 0 V$ Gate-Body Leakage Current, Forward $V_{GS} = 25 V, V_{DS} = 0 V$ Gate-Body Leakage Current, Reverse $V_{GS} = -25 V, V_{DS} = 0 V$ Gate Threshold Voltage $V_{DS} = V_{GS}, I_D = 250 \mu A$ Static Drain-Source 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On-Resistance $V_{DS} = 25 V, V_{GS} = 0 V,$ Forward Transconductance $V_{DS} = 25 V, V_{GS} = 0 V,$ Input Capacitance $r = 1.0 MHz$ mg CharacteristicsTurn-On Delay TimeTurn-Off Fall Time $(Note 4)$ Turn-Off Fall Time $V_{OS} = 48 V, I_D = 30 A,$ Gate-Drain Charge $V_{GS} = 10 V$ Gate-Drain Charge $V_{GS} = 10 V$	ParameterTest ConditionsMinTypracteristicsDrain-Source Breakdown Voltage $V_{GS} = 0 V, I_D = 250 \mu A$ 60Breakdown Voltage Temperature Coefficient $I_D = 250 \mu A$ , Referenced to $25^{\circ}C$ 0.06Zero Gate Voltage Drain Current $V_{DS} = 60 V, V_{GS} = 0 V$ Gate-Body Leakage Current, Forward $V_{GS} = 25 V, V_{DS} = 0 V$ Gate-Body Leakage Current, Reverse $V_{GS} = -25 V, V_{DS} = 0 V$ racteristicsGate Threshold Voltage $V_{DS} = V_{GS}, I_D = 250 \mu A$ 2.0Static Drain-SourceOn-Resistance $V_{GS} = 10 V, I_D = 15 A$ 16C CharacteristicsInput Capacitance $V_{DS} = 25 V, V_{GS} = 0 V,$ 725Output Capacitance $V_{DS} = 25 V, V_{GS} = 0 V,$ 725Output Capacitance $V_{DS} = 25 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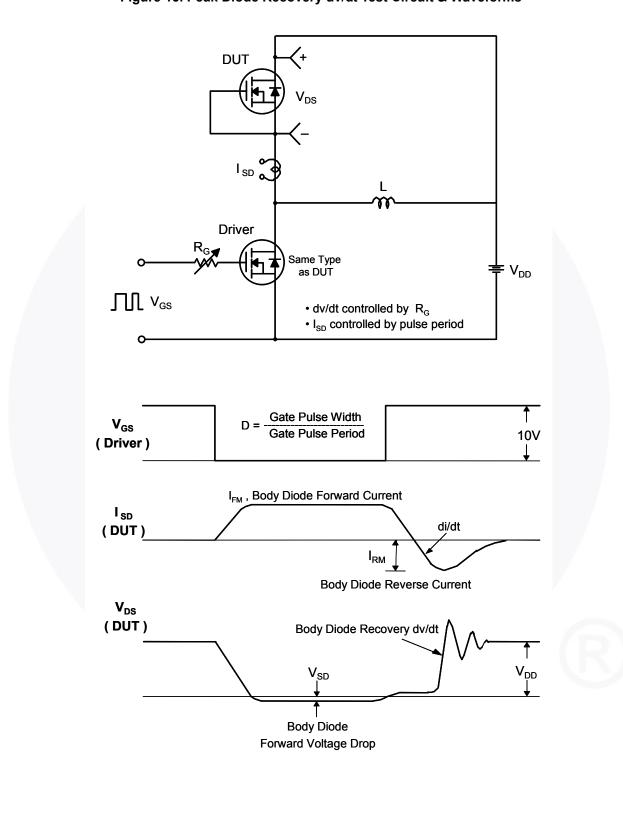
FQP30N06 — N-Channel QFET<sup>®</sup> MOSFET

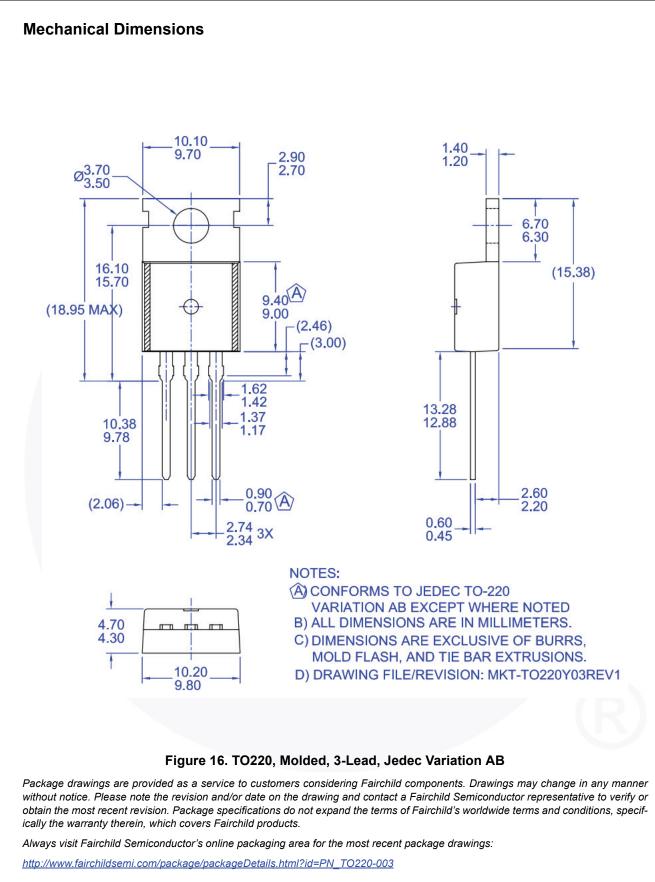




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